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| DOCUMENT CONTROL INFO | Customer: Company XYZ | Project Control Number: 03021 |
| | Project Name: Custom LED Interior... | Document Control Number: 008 |
| | Revision: 0 | BOM on File: YES |
| | Start Date: 2/19/2008 | Schematic Capture on File: YES |
| | Applications Engineer: Josh M. | Expected Completion: 2/28/2008 |
| | Design Engineer: Jeff M. | Notes: |
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The following items pertain to design specifics not previously addressed and documented, or not previously addressed and documented in detail. Noted items may affect the operation as based on design parameters stated in previous documents, and require client approval.

1. LED drive current as set by corresponding current limiting resistor (R1-R12) shall not exceed 75% of the LEDs maximum current rating at 25 degrees Celsius. Expected current draw per LED is 22.5 mA.
2. Resistor (R1-R12) power dissipation shall not exceed 50% of the 0.25-watt maximum rating. Expected power dissipation is less than or equal to 40 mW per resistor.
3. Maximum current draw shall not exceed 300 mA. Expected current draw is approximately 270 mA.
4. Maximum overall power dissipation shall not exceed 3.6 watts. Expected overall power dissipation is approximately 3.2 watts.
5. Printed circuit board copper cladding shall be 1 ounce copper before plating. Copper surface area shall cover the maximum possible surface area in direct proximity to components. Board house electrical testing required.
6. Wire terminals shall measure 0.043 inch in diameter.
7. Bare board panel arrays shall contain no greater than 32 boards-up, to enable assembly by automated insertion equipment.
8. Refer to document control number 006 for bill of materials and document control number 007 for schematic capture.